
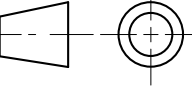


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Description		
Controle par :		Autorise par:
 ON semiconductor	Definition ASSEMBLY DRAWING BOTTOM PLAN EQUIPEMENT SOUDURE	
	Subc. <b>DYPE TECH</b>	Dessine: e B
Board: <b>NCP1618 C TLS</b>		Echelle: 1/1
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